
October 21 (Wed.), 2026

[Oral 08] CMP Consumables (I)

15:10-16:35

International Conference Hall (B1F)

● Session Chair: Xinping Qu (Fudan Univ., China)

15:10-15:35 **[Invited]** Advanced Ceria Slurries for SiO₂ CMP: Polishing Mechanism of
[Oral 08-1] Nanoceria and Emerging Applications

Hisataka Minami (Resonac Corp., Japan)

15:35-15:55
★[Oral 08-2] W CMP Oxidants for Ultra-low Chemical Dissolution with High Removal Rate

Yearin Byun, Thanh Cuong Nguyen, Inkwon Kim, Heechul Moon, and
Sangkyun Kim (Samsung Electronics Co., Ltd., Korea)

15:55-16:15 Advanced Soft Pad Conditioning Solutions for Improved Pad Life and
[Oral 08-3] Defectivity in Cu Barrier Applications

Uma Rames Krishna Lagudu, Chikai Chiu, Prasoon Gupta, Jiadi Fan (3M, USA),
Holden Lee, Chung I Ho, Jason Lin, Yuhsun Wang (3M, Taiwan), Changwan
Bea, Yoonghee Na (3M, Korea), Inki Kim (3M, USA), Benson Chen (3M,
Taiwan), and Yongsuk Yang (3M, Korea)

16:15-16:35
[Oral 08-4] CMP Process and Slurries for Memory Device Stacking

Yuchun Wang (Anji Microelectronics, China)